

Figure 10. Cross section of device embedded substrate

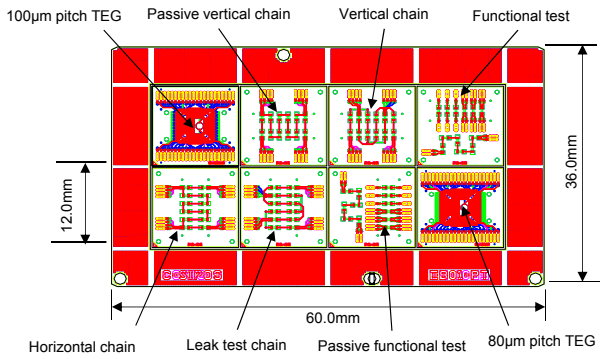


Figure 11. Evaluation kit of device embedded substrate SIPOS_EB01

Figure 11 shows the evaluation kit SIPOS_EB01 for device embedded substrates. This kit has been used in order for device companies to perform the functional test of discrete devices embedded inside the substrate with common substrate structure.

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